



100% Material Declaration Data Sheet TQG100

PK125 (v1.2.1) October 19, 2006

Material Declaration Data Sheet

Average Weight: 0.7 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.03787	5.41%
	Silicon	7440-21-3	100.00		0.03787	
Die Attach Material					0.00504	0.72%
	Silver	7440-22-4	78.00		0.0039312	
	Epoxy (EP)	Trade Secret	22.00		0.0011088	
Mold Compound					0.46396	66.28%
	Epoxy Resin (EP)	Trade Secret	9.00		0.0417564	
	Phenolic Resin	Trade Secret	7.00		0.0324772	
	Carbon Black	1333-86-4	0.50		0.0023198	
	Silica	60676-86-0	82.50		0.382767	
	Bismuth	7440-69-9	Max 1.00		0.0046396	
Leadframe					0.17885	25.55%
	Copper	7440-50-8	98.85		0.176793225	
	Chromium	7440-47-3	0.30		0.00053655	
	Tin	7440-31-5	0.25		0.000447125	
	Zinc	7440-66-6	0.60		0.0010731	
Leadframe Plating					0.00455	0.65%
	Silver	7440-22-4	100.00		0.00455	
Bond Wire					0.00357	0.51%
	Gold	7440-57-5	100.00		0.00357	
Ext. Plating					0.00616	0.88%
	Tin	7440-31-5	100.00		0.00616	

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Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
2/09/06	1.0	Initial release.
7/10/06	1.1	100% Material Declaration.
9/28/06	1.2	Updated component descriptions.
10/19/06	1.2.1	Editorial change; corrected typo in Substance Description.